Product Information

Jan 2016

# Ultramid<sup>®</sup> A3L HP BK20465 Polyamide 66



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# **Product Description**

Ultramid A3L HP BK20465 is an unreinforced, heat stabilized, impact modified, high flow, nylon 66 for injection molding. This grade has excellent flow and improved ambient and low temperature toughness.

# **Applications**

Typical applications include fasteners and clamps.

PHYSICAL	ISO Test Method	Property Value	
Density, g/cm³ MECHANICAL	1183 ISO Test Method	1.10	
		Dry	Conditioned
Fensile Modulus, MPa	527		
23°C		2,440	1,370
「ensile stress at yield, MPa	527		
23°C		63	44
ensile stress at break, MPa	527		
23°C		49	41
「ensile strain at yield, %	527		
23°C		6.2	25
lominal strain at break, %	527		
23°C		28	>50
Flexural Strength, MPa	178		
23°C		85	45
lexural Modulus, MPa	178		
23°C		2,280	1,150
MPACT	ISO Test Method	Dry	Conditioned
zod Notched Impact, kJ/m <sup>2</sup>	180		
-40°C		12	9.4
23°C		18	29
Charpy Notched, kJ/m <sup>2</sup>	179		
-30°C		14	11
23°C		19	28
Charpy Unnotched, kJ/m <sup>2</sup>	179		
-30°C		NB	NB
23°C		NB	NB
HERMAL	ISO Test Method	Dry	Conditioned
Melting Point, °C	3146	260	-
HDT A, ° C	75	70	-
HDT B, ° C	75	196	-
IL RATINGS	UL Test Method	Property Value	
Flammability Rating, 0.75mm	UL94	НВ	
Relative Temperature Index, 0.75mm	UL746B		
Mechanical w/o Impact, °C		110	
Mechanical w/ Impact, °C		105	
Electrical, °C		140	
lammability Rating, 3.0mm	UL94	НВ	
Relative Temperature Index, 3.0mm	UL746B		
Mechanical w/o Impact, °C		110	
Mechanical w/ Impact, °C		105	
Electrical, °C			140

#### **Processing Guidelines**

# **Material Handling**

Nylon 66 materials must be properly dried in order to provide parts with optimum strength and toughness. Nylon 66 materials are hygroscopic and will become degraded by excessive moisture during the injection molding process. For unopened bag/box, dry at 60 degC (140 degF) for 1-2 hours. For material exposed to the atmosphere, if additional drying is needed, dry at 66 degC (150 degF) or until the moisture level is between 0.04 - 0.20%.

# **Typical Profile**

Melt Temperature: 288-305 degC (550-581 degF) Mold Temperature: 60-100 degC (140-212 degF) Injection Pressure: 35-125 MPa (5000-18000 psi)

Back Pressure: 0-0.35 MPa (0-50 psi) Screw RPM 40-80 Screw Compression Ratio:3:1-4:1

#### **Mold Temperatures**

This product can be processed over a wide range of mold temperatures; however, for applications where aesthetics are critical, a mold surface temperature of 60-100 degC (140-212 degF) is recommended.

#### Pressures

Injection pressure controls the filling of the part and should be applied for 90% of ram travel. Packing pressure affects the final part and can be used effectively in controlling sink marks and shrinkage. It should be applied and maintained until the gate area is completely frozen off.

#### Fill Rate

Fast fill rates are recommended to ensure uniform melt delivery to the cavity and prevent premature freezing.

#### Note

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